



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSO130P03S H	<b>Issued</b>	12. August 2021
<b>MA#</b>	MA005617669		
<b>Package</b>	PG-DSO-8-39	<b>Weight*</b>	83.83 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.447	2.92	2.92	29186	29186
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		122	
	non noble metal	zinc	7440-66-6	0.041	0.05		489	
	non noble metal	iron	7439-89-6	0.820	0.98		9777	
	non noble metal	copper	7440-50-8	33.276	39.70	40.74	396969	407357
wire	non noble metal	copper	7440-50-8	0.189	0.23	0.23	2255	2255
encapsulation	organic material	carbon black	1333-86-4	0.227	0.27		2710	
	plastics	epoxy resin	-	7.042	8.40		84009	
	inorganic material	silicondioxide	60676-86-0	38.163	45.52	54.19	455274	541993
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9709	9709
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	866	866
glue	plastics	epoxy resin	-	0.109	0.13		1295	
	noble metal	silver	7440-22-4	0.615	0.73	0.86	7339	8634
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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